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Press Release

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**Boulder, CO – September 11, 2009** – Tech-X Corporation invites you to visit us at our booth at the [International Conference on Ion Sources](#), September 20 - 24, 2009, in Gatlinburg, TN.

Tech-X is proud to present the latest release of our electromagnetic plasma simulation software, [VORPAL](#). **For the first time, VORPAL 4.0 provides parallel and multi-core capability to the Windows platform** (as with previous versions, VORPAL 4.0 also runs in parallel on the Linux and Macintosh platforms). Let VORPAL 4.0 help you take full advantage of your multi-core desktop computer. Other new capabilities include:

- cylindrical coordinates for electromagnetic simulation
- automated eigenfrequency and eigenmode extraction from time-domain simulation
- new secondary electron models that allow simulations of complex metallic and dielectric boundaries of arbitrary shape without stairsteps
- improved post-processing, including automated import into the VisIt software for advanced visualization
- improved documentation, including a detailed, 180-page reference manual, a 160-page user guide, and a 157-page examples guide